

HV459 SERIES

8 to 12kV, 650 to 1100mA, 75nS to Standard Recovery High Voltage Modules



Features

- Encapsulated High Current Rectifier Module
- Large Surface Area for Distributed Heat Transfer
- Aids in Efficient Utilization of PC Board Area

Specifications¹

Drawings

Part Number	V _{RRM} V	I _{FAVM1} mA	I _{FAVM2} mA	V _F V	Ι _R μΑ	I _{FSM} A	С _Ј pF	T _{RR} ² nS
Standard Recovery Subseries								
HV459S8	8000	1100	2000	10.0	10	80	-	-
HV459S10	10000	970	2000	12.5	10	80	-	-
HV459S12	12000	850	2000	15.0	10	80	-	-
Ultra Fast Recovery Subseries								
HV459U8	8000	850	1500	10.7	10	45	8.3	75
HV459U10	10000	750	1500	13.4	10	45	6.6	75
HV459U12	12000	650	1500	16.1	10	45	5.5	75

Temperature °C				
Storage Temperature	-40 to 150			
Operating Temperature	-40 to 150			

¹25°C ambient temperature unless stated otherwise.

 ^2A "-" indicates that the component is a standard recovery device and no T_{RR} data is taken.



Dimensions in inches, tolerances ± 0.020 except as noted



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Specification Definitions

	Specifications	Conditions
V _{RRM}	Maximum Repetitive Reverse Voltage	-
IFAVM1	Maximum Average Forward Current	At $T_A = 25^{\circ}C$
IFAVM2	Maximum Average Forward Current	At $T_A = 55^{\circ}C$, in Oil
VF	Maximum Forward Voltage Drop	At 100mA
I _R	Maximum Leakage Current	At V _{RRM}
IFSM	Maximum Surge Current	At 8.3 mS, Single Half Sine
CJ	Typical Junction Capacitance	At $V_R = 0VDC$, f = 1MHz
T _{RR}	Maximum Reverse Recovery Time	IF = 0.5 IFAVM1; IR = - IFAVM1; IRR = -0.25 IFAVM1



Note: Specifications subject to change without notice. Photo is representation only.



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